PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHUBHADA H SAHASRABUDHE	11/09/2015
SANDEEP B SANE	11/09/2015
SIDDARTH KUMAR	11/08/2015
SHALABH TANDON	11/09/2015

RECEIVING PARTY DATA

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Street Address:	2200 MISSION COLLEGE BLVD.
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Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14937022

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	884.T27US1
NAME OF SUBMITTER:	NANCY CUNDALL
SIGNATURE:	/ Nancy Cundall /
DATE SIGNED:	12/07/2015

Total Attachments: 3

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RECORDATION FORM COVER SHEET PATENTS ONLY

Atty Ref/Docket No.: 884.T27US1 To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof. 2. Name and address of receiving party(ies): 1. Name of conveying party(ies): Name: Intel Corporation Shubhada H. Sahasrabudhe, Sandeep B Sane, Siddarth Street Address: 2200 Mission College Blvd. Kumar, Shalabh Tandon Additional name(s) of conveying party(ies) attached? City: Santa Clara State: CA Zip: 95054 Country: United States of America []Yes [X]No Additional name(s) & address(es) attached? []Yes [X]No 3. Nature of conveyance: [] Merger [X] Assignment [] Security Agreement [] Change of Name [] Other Execution Date: November 9, 2015, November 9, 2015, November 8, 2015, November 9, 2015 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) B. Patent No.(s) Serial No. 14/937,022 Additional numbers attached? []Yes [X]No 6. Total number of applications and patents involved: 1 5. Name and address of party to whom correspondence concerning document should be mailed: 7. Total fee (37 CFR 3.41):\$ <u>0.00</u> Name: Rigel J. Menard [[Enclosed [Authorized to be charged to deposit account Address: 504238 Schwegman Lundberg & Woessner, P.A. P.O. Box 2938 Please charge any additional fees or credit any over Minneapolis, MN 55402--0938 payments to our Deposit Account No.: 504238 DO NOT USE THIS SPACE Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Rigel J. Menard/Reg. No. 66,520 /Rigel J Menard/ Name of Person Signing Signature Total number of pages including cover sheet: 3

Mail documents to be recorded with required cover sheet information to:

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Patent and Trademark Office

Intel Docket No.: P86044 SLW Reference No.: 884.T27US1

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Shubhada H. Sahasrabudhe, Sandeep B Sane, Siddarth Kumar, Shalabh Tandon>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

SYSTEMS AND METHODS FOR PACKAGE ON PACKAGE THROUGH MOLD INTERCONNECTS

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)					
which was filed on November 10, 20)15 as				

United States of America	Application Number	14/937,022	
Country or International Office	* 2		

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute

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all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors. assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives: and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, neense, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Shubhada H. Sahasrabudhe

Shalabh Tandon

Nov. 9 , 2015 .

Date Signed

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Date Signed

Note Signed

November 9,2015

Date Signed

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